



# DuPont™ EKC PCMP5000™

Post Chemical Mechanical Planarization Cleaners

For Copper/Low-K Post-CMP Cleaning

The DuPont™ EKC PCMP5000™ post chemical mechanical planarization (PCMP) cleaners have been developed to meet the advanced needs of the semiconductor manufacturing industry. The company's reputation and products are built on focused chemical expertise and high quality, high purity raw materials, combined to provide the performance and consistency required for today's semiconductor production processes.

DuPont™ EKC PCMP5000™ series products are excellent PCMP cleaning solutions for use following copper and tungsten chemical mechanical planarization (CMP). These aqueous cleaning solutions offer outstanding results, including removal of residual metals and particles. EKC PCMP5000™ products do not contain any fluorides, they contain no TMAH, benzotriazole or similar species, or fluoride. All components are water-miscible and aqueous drain compatible. EKC PCMP5000™ series products are also fully compatible with double side scrubbers, megasonic cleaning equipment and standard wet benches.

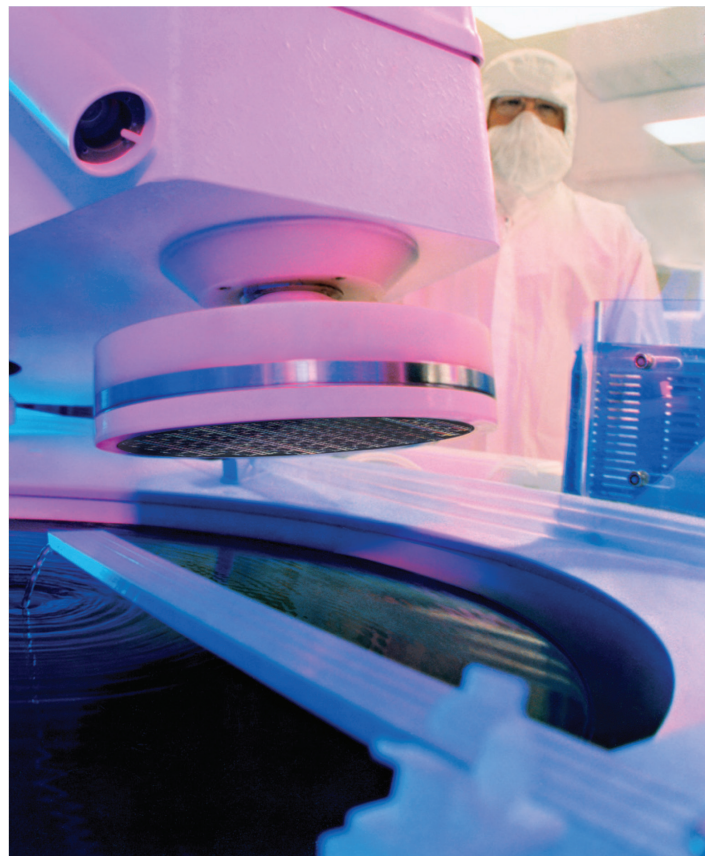
## **DuPont™ EKC PCMP5000™ series post chemical mechanical planarization cleaners include:**

### **EKC PCMP5500™**

Acidic PCMP product designed for challenging particle and mobile metal ion removal following tungsten planarization.

### **EKC PCMP5510™**

Neutral pH post-CMP product optimized for metal ion and particles removal and excellent copper and dielectric compatibility.





[ekctech.dupont.com](http://ekctech.dupont.com)

For more information on DuPont™ EKC PCMP5000™ or other DuPont products, please visit our website.

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**CAUTION:** Do not use in medical applications involving permanent implantation in the human body. For other medical applications, see "DuPont Medical Caution Statement," H-50102-5 and "DuPont Policy Regarding Medical Applications" H-50103-5.

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K-10776-3 (05/19)